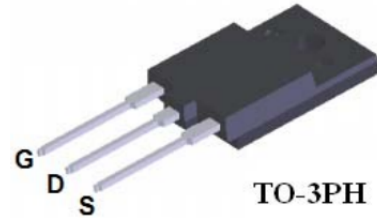


## 1500V N-Channel MOSFET

### General Description

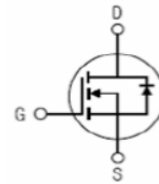
This Power MOSFET is produced using advanced self-aligned planar technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices can be used in various power switching circuit for system miniaturization and higher efficiency.



TO-3PH

Inner Equivalent Principium Chart



### Features

- 3A, 1500V,  $R_{DS(on)}$  typ. =  $5\Omega$  @  $V_{GS} = 10V$   $I_d = 1.5A$
- Low gate charge (typical 37nC)
- Low reverse transfer capacitance (typical 2.8pf)
- Fast switching
- 100% avalanche tested

## Absolute Maximum Ratings $T_c = 25^\circ C$ unless otherwise noted

Symbol	Parameter	YZPST-QM3N150C	Units
$V_{DSS}$	Drain – Source Voltage	1500	V
$I_D$	Drain Current	Continuous ( $T_c = 25^\circ C$ )	3
		Continuous ( $T_c = 100^\circ C$ )	1.8
$I_{DM}$	Drain Current - Pulsed ( Note 1 )	12	A
$V_{GS}$	Gate – Source Voltage	$\pm 30$	V
EAS	Single Pulsed Avalanche Energy ( Note 2 )	225	mJ
dv/dt	Peak Diode Recovery dv/dt ( Note 3 )	5	V/ns
$P_D$	Power Dissipation ( $T_c = 25^\circ C$ )	32	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ C$
$T_L$	Maximum lead temperature for soldering purposes	300	$^\circ C$
	1/8" from case for 5 seconds		

\*Drain current limited by maximum junction temperature.

## Thermal characteristics

Symbol	Parameter	YZPST-QM3N150C	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.8	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	40	$^\circ C/W$

**Electrical Characteristics**  $T_c = 25\text{ }^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain – Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	1500	--	--	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , Referenced to $25\text{ }^\circ\text{C}$	--	1.5	--	V/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 1500\text{ V}, V_{GS} = 0\text{ V}$	--	--	25	$\mu\text{A}$
		$V_{DS} = 1200\text{ V}, T_c = 125\text{ }^\circ\text{C}$	--	--	500	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage ( Note 4 )	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	3.0	--	5.0	V
$R_{DS(on)}$	Static Drain-Source on-Resistance ( Note 4 )	$V_{GS} = 10\text{ V}, I_D = 1.5\text{ A}$	--	5	8	$\Omega$
$g_{fs}$	Forward Transconductance ( Note 4 )	$V_{DS} = 30\text{ V}, I_D = 1.5\text{ A}$	--	4.5	--	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	--	1938	--	pF
$C_{oss}$	Output Capacitance		--	104	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	2.8	--	pF
$R_g$	Gate resistance	$F = 1.0\text{ MHz}$	--	4.0	--	$\Omega$
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 750\text{ V}, I_D = 3.0\text{ A}, R_G = 10\text{ }\Omega, V_{GS} = 10\text{ V}$ ( Note 4,5 )	--	35	--	ns
$t_r$	Turn-On Rise Time		--	19	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	56	--	ns
$t_f$	Turn-Off Fall Time		--	30	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 750\text{ V}, I_D = 3.0\text{ A}, V_{GS} = 10\text{ V}$ ( Note 4,5 )	--	37	--	nC
$Q_{gs}$	Gate-Source Charge		--	10	--	nC
$Q_{gd}$	Gate-Drain Charge		--	14	--	nC
<b>Drain – Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain-Source Diode Forward Current		--	--	3	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current		--	--	12	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 3.0\text{ A}$	--	--	1.5	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = 3.0\text{ A}$	--	880	--	ns
$Q_{rr}$	Reverse Recovery Charge	$di_f/dt = 100\text{ A}/\mu\text{s}$ ( Note 4 )	--	6.5	--	$\mu\text{C}$

**Notes:**

1. Repetitive Rating : Pulsed width limited by maximum junction temperature
2.  $L = 10.0\text{ mH}$ ,  $I_{AS} = 6.7\text{ A}$ ,  $R_G = 25\text{ }\Omega$ , Starting  $T_j = 25\text{ }^\circ\text{C}$
3.  $I_{SD} \leq 3.0\text{ A}$ ,  $di/dt \leq 100\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_j = 25\text{ }^\circ\text{C}$
4. Pulsed Test : Pulsed width  $\leq 300\text{ }\mu\text{s}$ , Duty cycle  $\leq 2\%$
5. Essentially independent of operating temperature

Characteristics Curve

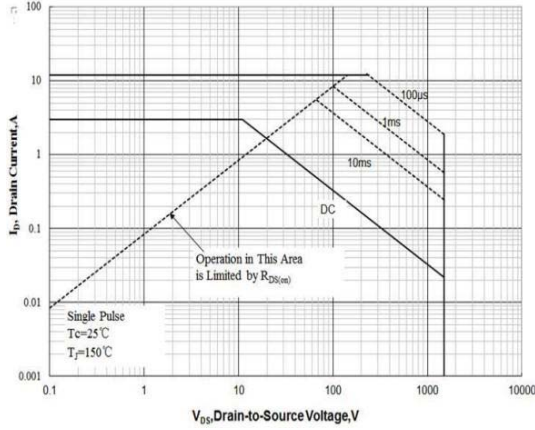


Figure 1 Maximum Forward Bias Safe Operating Area

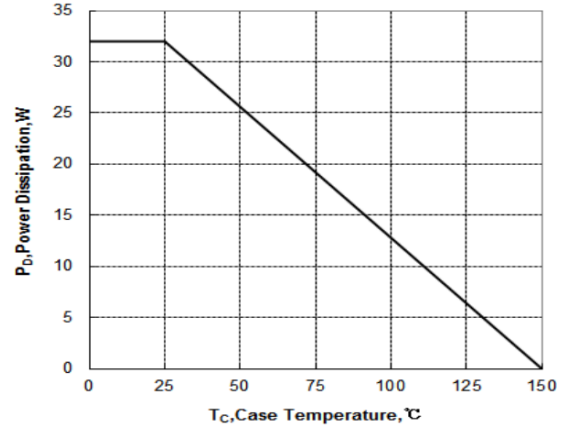


Figure 2 Maximum Power dissipation vs Case Temperature

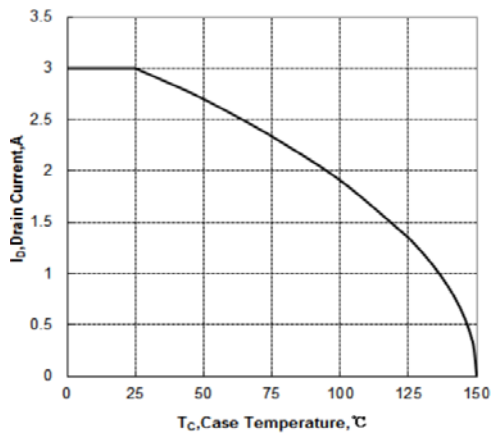


Figure 3 Maximum Continuous Drain Current vs Case Temperature

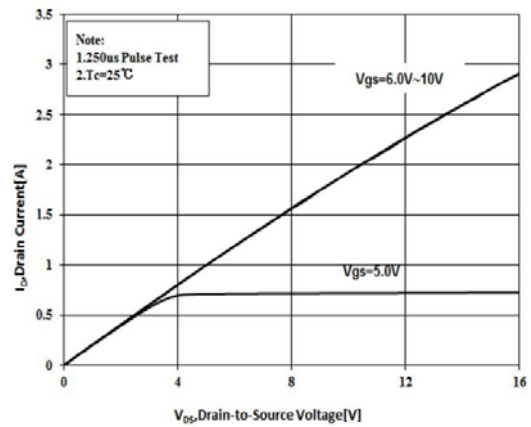


Figure 4 Typical Output Characteristics

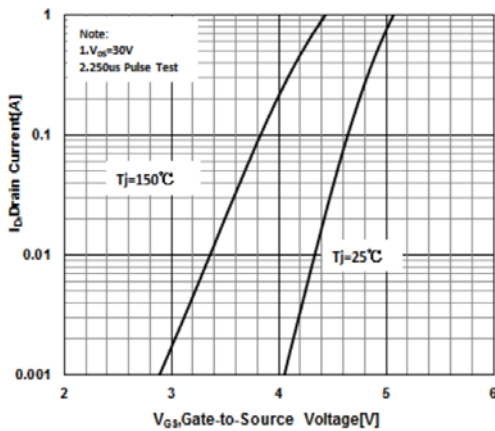


Figure 5 Typical Transfer Characteristics

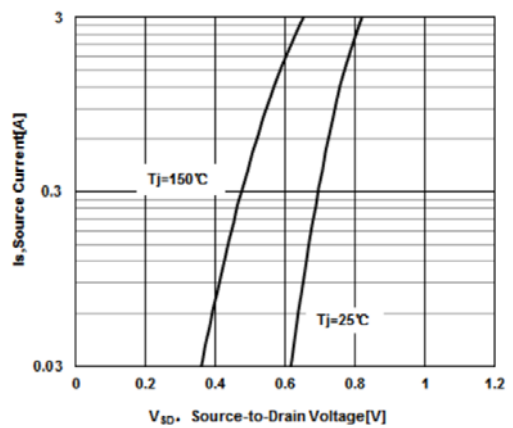


Figure 6 Typical Body Diode Transfer Characteristics

Characteristics Curve

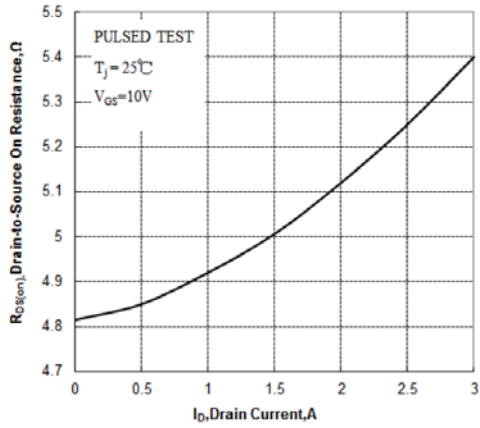


Figure 7 Typical Drain to Source ON Resistance vs Drain Current

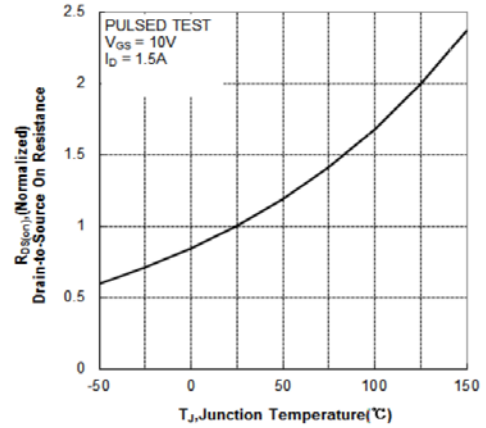


Figure 8 Typical Drian to Source on Resistance vs Junction Temperature

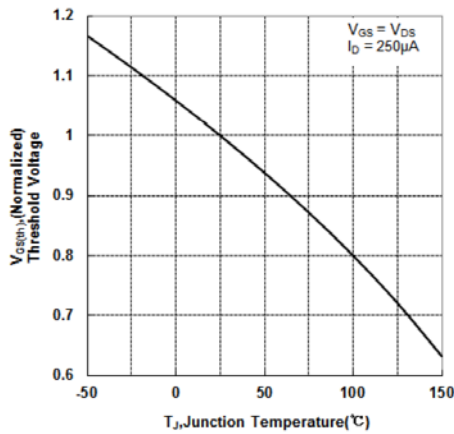


Figure 9 Typical Theshold Voltage vs Junction Temperature

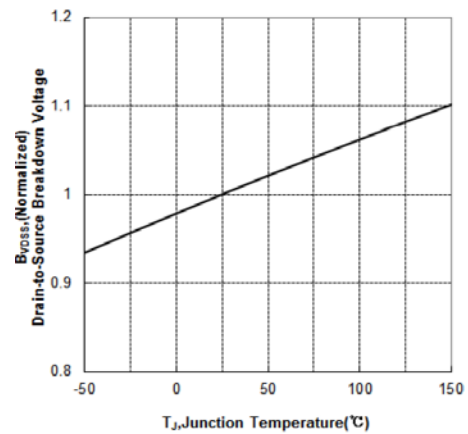


Figure 10 Typical Breakdown Voltage vs Junction Temperature

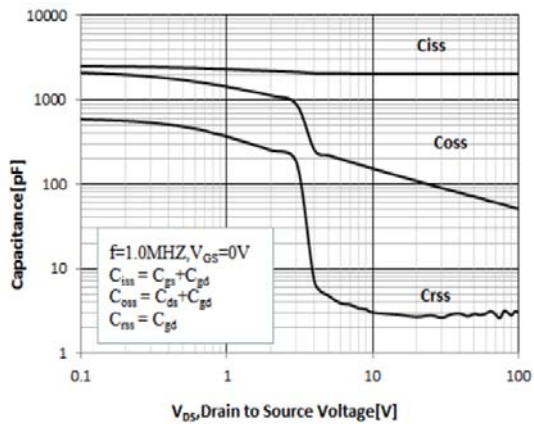


Figure 11 Typical Capacitance vs Drain to Source Voltage

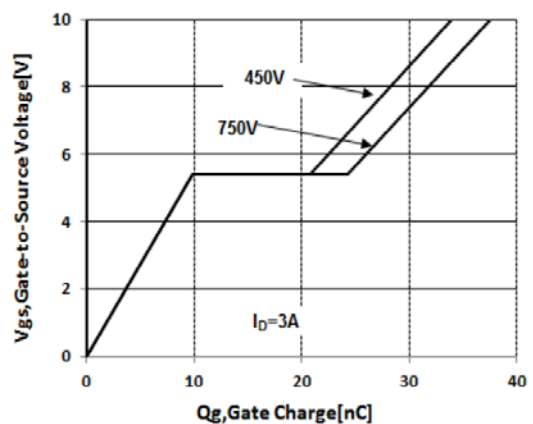


Figure 12 Typical Gate Charge vs Gate to Source Voltage

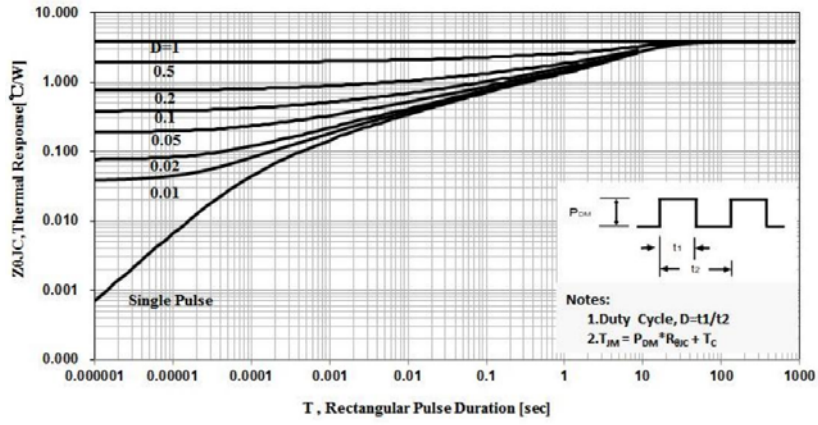
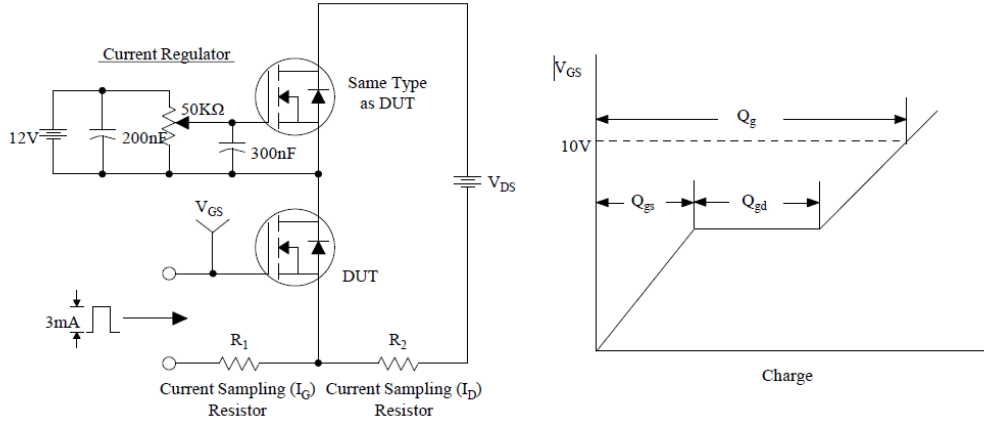
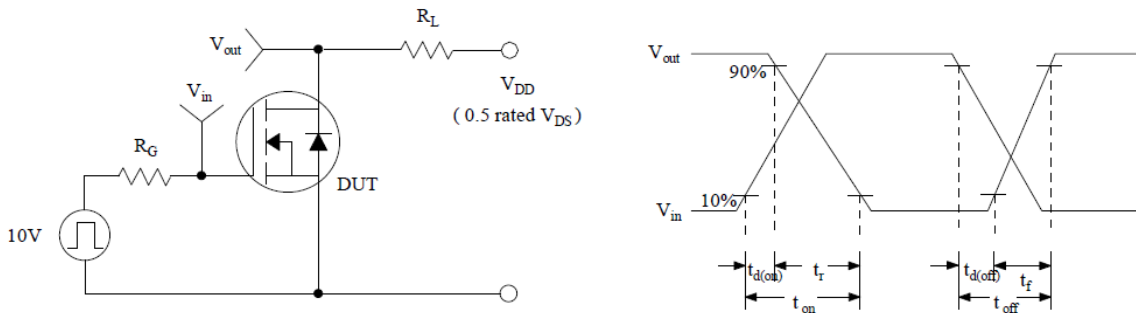


Figure 13 Maximum Effective Thermal Impedance , Junction to Case

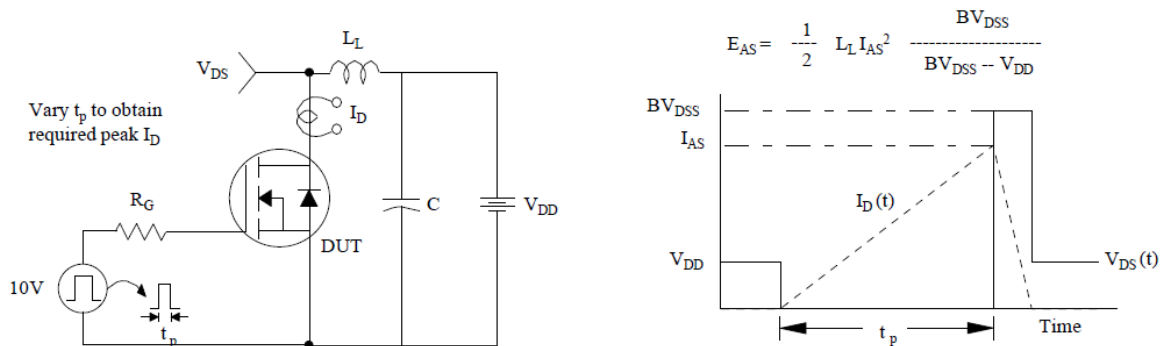
**Test Circuit & Waveform**



Gate Charge Test Circuit & Waveform



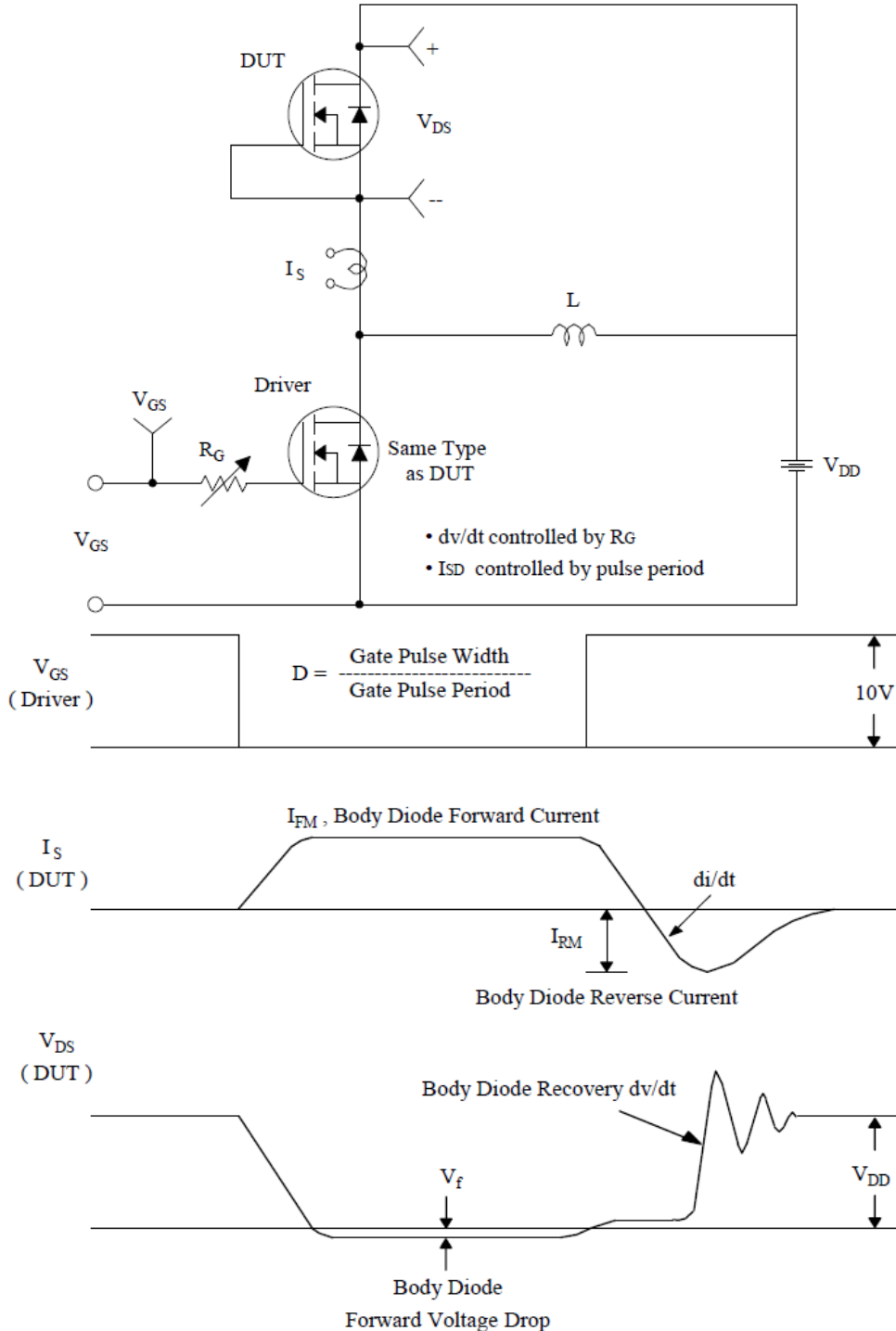
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

$$E_{AS} = \frac{1}{2} L_L I_{AS}^2 \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

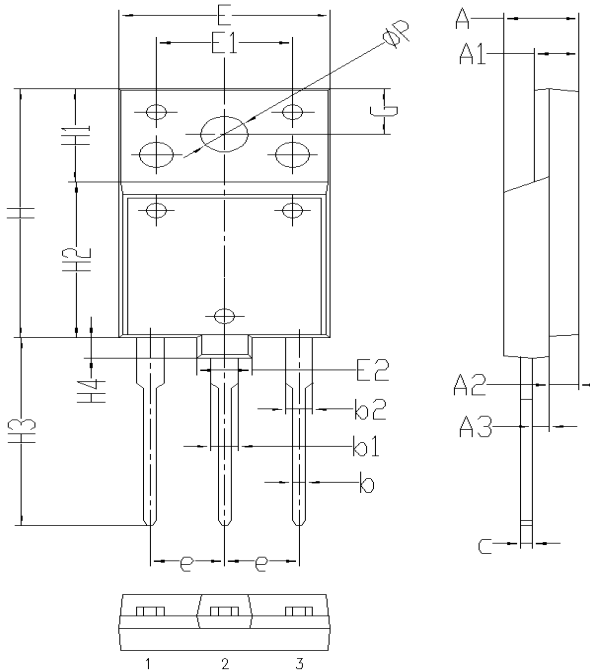
**Test Circuit & Waveform**



Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms



**TO-3PH Package Information**



Symbol	单位 mm		
	Min	Nom	Max
A	5.35	5.55	5.75
A1	2.80	3.00	3.20
A2	1.90	2.10	2.30
A3	1.10	1.30	1.50
b	0.65	0.75	0.85
b1	1.80	2.00	2.20
b2	1.80	2.00	2.20
c	0.70	0.90	1.10
e	5.25	5.45	5.65
E	15.3	15.5	15.7
E1	9.80	10.0	10.2
E2	3.80	4.00	4.20
H	24.3	24.5	24.7
H1	9.00	9.20	9.40
H2	15.1	15.3	15.5
H3	18.5	19.0	19.5
H4	1.80	2.00	2.20
H5	4.80	5.00	5.20
G	4.3	4.5	4.7
ΦP	3.40	3.60	3.80